

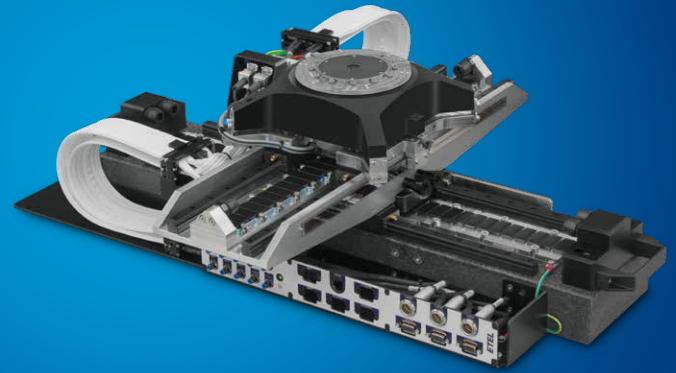


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CHARON2 Stacked System

ETEL

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ETEL

The CHARON2 platform is built on a robust, reliable and elegantly simple stacked architecture, designed with modularity and scalability principles in mind. Its compatibility with current and future modules and options allows coverage of the broadest application space and use cases. Continuously evolving in all served markets, CHARON2 supports OEM's product lifetime extension as well as upgrade paths.

With all-conditions field proven decades of uninterrupted operations and large manufactured volumes of this architecture, CHARON2 represents the most flexible entry point for turn-key motion solutions and sets a new record in price-per-performance ratio.

CHARON2 delivers a minimum dynamic of 1 g acceleration and of 1 m/s speed. Its position accuracy of 1 μm level paired with excellent bidirectional repeatability sustains applications development in all technology and industry fields. From this platform originates standard product configurations, for immediate integration, and customized solutions, accommodating suited performance needs.

CHARON2 STACKED SYSTEM

This system can also be integrated with ETEL's QuiET Active Isolation System to reach ultimate performance.



CHARON2 remains another perfect example of ETEL vertical integration, based on proprietary IP for motors, electronics and controlling know-how, and synergy with HEIDENHAIN when relating to world-class positioning accuracy feedback.

The result is a broad family of solutions serving any OEM wafer-positioning needs, process or process-control related, and ranging from a core X to a complete system of up to 7 axes, independently controlled and actively isolated.

CHARON2 stems from anticipated, aligned, OEM requirements immediately fulfilled with another optimized product, reducing OEM integration costs and time-to-market efforts.

PERFORMANCE

	X (Bottom)	Y (Upper)	THETA
Speed	± 1 m/s	± 1 m/s	41.8 rad/s
Acceleration	10 m/s ²	10 m/s ²	2200 rad/s ²
Position accuracy	± 1 μm	± 1 μm	± 3 arcsec
Position stability	± 2 nm	± 2 nm	± 0.02 arcsec
Bidir. repeatability	± 0.4 μm	± 0.4 μm	± 2 arcsec
Maximum payload	30 kg		

PRODUCT HIGHLIGHTS

- Total stroke: up to 650 mm x 410 mm
- Native ISO2, optional ISO1 compatibility
- Applications and use cases flexibility
- Best-in-class cost of ownership
- Modularity, scalable performance and field upgradeability
- Standard configurations available for immediate evaluation and prototyping

TYPICAL APPLICATIONS

- Semiconductor Manufacturing Process Control applications, such as Overlay / Critical Dimension, Thin Film, 4-point probe, Profilometry, Interferometry and many other metrology techniques
- Advanced packaging
- Visual inspection and characterization of parts
- Microscopy and spectroscopy
- High-precision machining